

DT1745H

Component Metallization

Description

DT1745H is a lead free Ag paste for front side conductor of chip resistors, with excellent leaching property, acid resistance, adhesion property and electrical characteristics.

Key Features

- Excellent leaching property Excellent acid resistance
Excellent adhesive property Excellent electrical characteristics



Typical Properties

Viscosity	200 – 400 kcps, Brookfield HBDV-III Ultra, SC4-14 spindle & 6R utility cup @ 10 rpm, 25°C
Solids	76.0 ± 2.0%
Solder Leaching	Sn96/Ag3.5/Cu0.5 260 °C >60 sec Coverage area >95%

Recommended Processing Guide

Printing Parameters	200- 400 mesh Polyester or stainless steel screen
Drying Temperature	130 °C for 15 minutes, with exhaust system 150 °C for 10 minutes
Process Temperature (TDS)	Peak temp : 840~860 °C Dwell time : 8~15 minutes
Recommended Thinner	Heraeus RV-372

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Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry, cool (5 - 25°C), dark place with container tightly shut. Allow paste to come to room temperature prior to opening. Spatulate well before using.

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